

REMARKS

Claims 1-4, 10-17, 19-21, 23 and 25-27 are pending in the present application. Claims 5-6, 18 and 22 were previously canceled. Claims 1-4, 10-17, 19-21, 23, 25 and 27 have been amended. No new matter has been added. Applicants respectfully request reconsideration of the claims in view of the following remarks.

Claims 1, 2, 4, and 26 have been rejected under 35 U.S.C. § 102(b) as being anticipated over Hedler, et al. (German Patent Application Number DE01010535A1, hereinafter "Hedler"), and claims 7-17, 19-21, 23-25, and 27 have been rejected under 35 U.S.C. § 103(a) as being unpatentable over Hedler. Applicants traverse these rejections.

Claim 1 has been amended to recite "after applying the casting compound, exposing separation corridors on the semiconductor wafer by removing portions of the casting compound." Hedler does not teach or suggest exposing separation corridors after applying casting compound. To the contrary, Hedler teaches exposing saw traces by using a silk screen process. Hedler translation, page 5, 8 lines from the bottom which corresponds to Hedler paragraph [0045]. A silk screen process does not remove material after it has been applied; rather it prevents material from being applied in the first place. Hedler, in fact, teaches away from removing already apply material from separation corridors by stating that "expensive photolithographic steps are avoided" when referring the application of a protective layer. Hedler translation, page 4, first line at the top which corresponds to Hedler paragraph [0032]. Applicants, therefore, respectfully submit that claim 1 is allowable over the prior art of record.

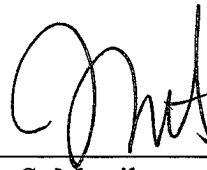
Claims 2-4, 10-17, 19-20, and 26-27 depend from claim 1 and add further limitations. It is respectfully submitted that these dependent claims are allowable by reason of depending from an allowable claim as well as for adding new limitations.

Claim 21 has been amended to recite "after the casting compound is applied, exposing separation corridors by removing portions of the casting compound, and wherein after the exposing the separation corridors." As is discussed with respect to claim 1, hereinabove, Hudler does not teach or suggest exposing separation corridors by removing portions of the casting compound. Applicants, therefore, respectfully submit that claim 21 is allowable over the prior art of record.

Claims 23 and 35 depend from claim 1 and add further limitations. It is respectfully submitted that these dependent claims are allowable by reason of depending from an allowable claim as well as for adding new limitations.

Applicants have made a diligent effort to place the claims in condition for allowance. However, should there remain unresolved issues that require adverse action, it is respectfully requested that the Examiner telephone Ira S. Matsil, Applicants' attorney, at 972-732-1001 so that such issues may be resolved as expeditiously as possible. In the event that the enclosed fees are insufficient, please charge any additional fees required to keep this application pending, or credit any overpayment, to Deposit Account No. 50-1065.

Respectfully submitted,



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Date

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